



Part number		NT_MCIS_v0010
Tip		
Material	HDC/DLC	
Shape	conical	
Tip length / l	400 nm	(±100 nm)
Diameter / d	n/a	
Half cone angle / Φ	<4°	(AR>5)
Radius / r	10 nm	(±2 nm)
Tilt compensation / θ	13°	(±1°)
Pyramid height / PH	15 μm	(10-15 μm)
Tip set back / TSB	15 μm	(5-25 μm)
Cantilever		
Material	Si	
Shape	NT-RTESPA	
Length / L	120 μm	(±5 μm)
Width / W	30 μm	(±2 μm)
Thickness / T	4.4 μm	(±0.5 μm)
Force constant / k	40 N/m	(±20 N/m)
Resonance Frequency / f	320 kHz	(±50 kHz)
Coating		
Tip side	none	
Back side	reflex	
Chip		
Length / L_Chip	3400 μm	
Width / W_Chip	1600 μm	
Thickness / T_Chip	315 μm	
Alignment grooves	no	

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